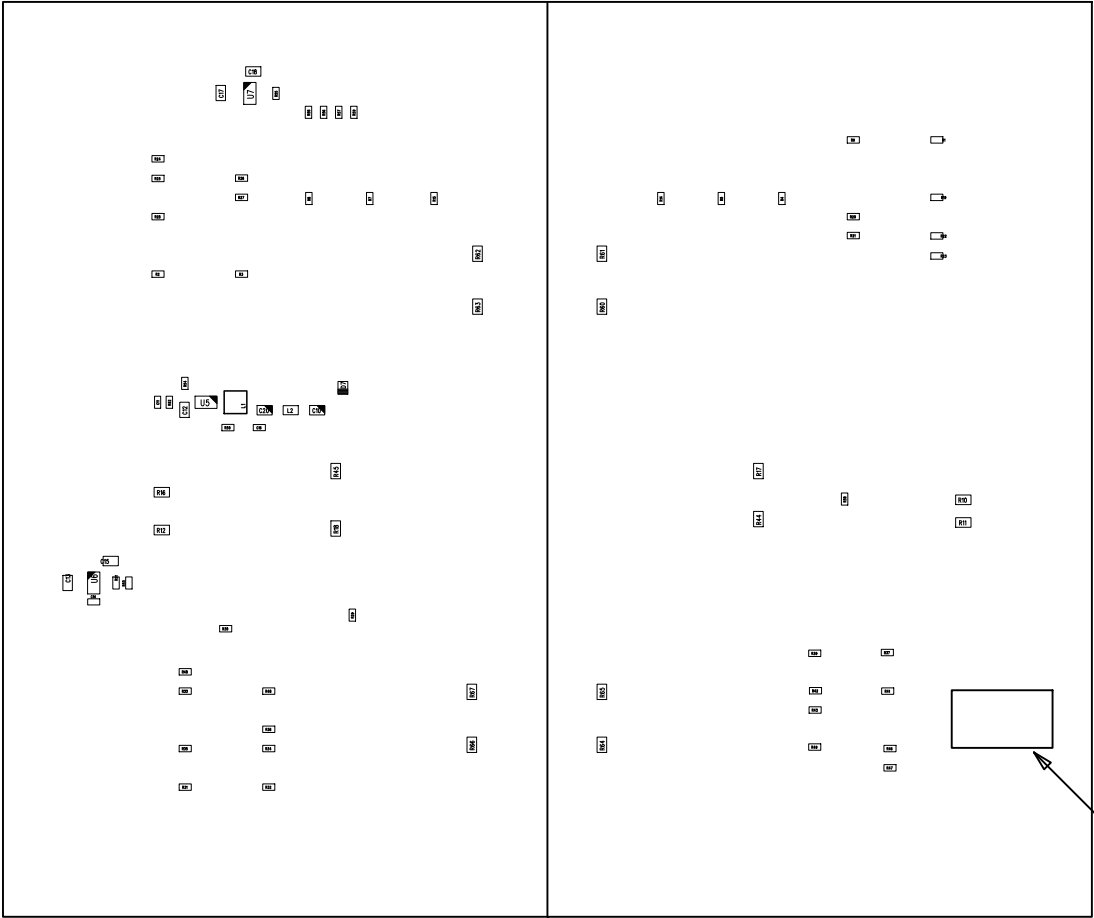



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
	3	Production	E Benedict	4 OCT 18



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
- 2. MAXIMUM SOLDER TEMPERATURE IS 250 DEG C.
- 3. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP AND BOTTOM SIDE SMD.
- 4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
- 5. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
- 6. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
- 7. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD
- 8. APPLY DEMO S/N LABEL IN THIS AREA
- 9. BREAK BOARDS AS A SET. DO NOT BREAK AT THIS LOCATION

APPROVALS		 <div>1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com ADI CONFIDENTIAL- FOR CUSTOMER USE ONLY</div>		
PCB DES.	EB			
APP ENG.	EB	TITLE: BOTTOM ASSEMBLY DEMO CIRCUIT RUGGED I2C SLAVE DEVICE EXTENDER		
		SIZE N/A	IC NO. LTC4331 DEMO CIRCUIT DC2754A	REV. 3
SCALE = NONE		SHT 2 OF 2		